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COOL Chips 20

Yokohama Joho Bunka Center, Yokohama, Japan
(Yokohama Media & Communications Center, Yokohama, Japan)
April 19 - 21, 2017

CALL FOR CONTRIBUTIONS

COOL Chips is an International Symposium initiated in 1998 to present advancement of low-power and high-speed chips. The symposium covers leading-edge technologies in all areas of microprocessors and their applications. The COOL Chips 20 is to be held in Yokohama on April 19-21, 2017, and is targeted at the architecture, design and implementation of chips with special emphasis on the areas listed below. All papers will be published online via IEEE Xplore. From this year's symposium, the COOL Chips Program Committee will ask the IEEE Transactions on Multi-Scale Computing Systems (TMSCS) to publish selected papers in a special issue on COOL Chips 20. Authors of industrial best papers will be recommended to submit an extended version to a COOL Chips special issue of IEEE Micro.

Contributions are solicited in the following areas:

 • **Low Power-High Performance Processors for -**
  Multimedia, Digital Consumer Electronics, Mobile, Graphics, Encryption, Robotics, Automotive, Networking, Medical, Healthcare, and Biometrics.
 • **Novel Architectures and Schemes for -**
  Single Core, Multi/Many-Core, NoC, Embedded Systems, Reconfigurable Computing, Grid, Ubiquitous, Dependable Computing, GALS and 3D Integration
 • **Cool Software including - Parallel Schedulers, Embedded Real-time Operating System, Binary Translations, Compiler Issues and Low Power Techniques.**

Proposals should consist of a title, an extended abstract (up to 3 pages) describing the product or topic to be presented and the name, job title, address, phone number, FAX number, and e-mail address of the presenter. The status of the product or topic should precisely be described. If this is a not-yet-announced product, and you would like to keep the submission confidential, please indicate it. We will do our best to maintain confidentiality. Proposals will be selected by the program committee's evaluation of interest to the audience. Submission should be made through website. Detailed instructions are in author's kit obtained from **http://www.coolchips.org/**.

Author Schedule:	February 6, 2017	Extended Abstract Submission (through website)
	March 8, 2017	Acceptance Notified (by e-mail)
	March 31, 2017	Final Manuscript Submission

You are also invited to submit proposals for poster sessions. Submission should be made through website. Detailed instructions are in author's kit obtained from **http://www.coolchips.org/**.

Author Schedule:	March 15, 2017	Poster Abstract Submission (through website)
	March 22, 2017	Poster Acceptance Notified (by e-mail)

For more information, please visit <**http://www.coolchips.org/**>.
For any questions, please contact the Secretariat <**cool_20@coolchips.org**>.

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(As of November 24, 2016)